

Product- information Type: PG3030/10/SE/SF

Group: Special heatsinks, Finger shaped heatsinks

Heatsinks for Microprocessors (PGA, BGA, IC)

Application (Cases):	PGA, BGA, IC
Number of semiconductors:	1
Mounting of semiconductors :	to glue
Mounting of heatsinks:	to glue
Finish:	black anodized
Thermal resistance:	9.6 K/W
Material:	AlMgSi 0,5

